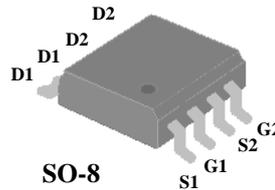


- ▼ Low On-Resistance
- ▼ Capable of 2.5V Gate Drive
- ▼ Dual N MOSFET Package
- ▼ RoHS Compliant & Halogen-Free

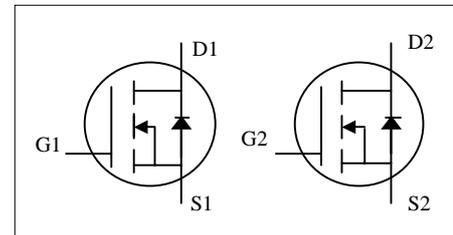


BV_{DSS}	20V
$R_{DS(ON)}$	14m Ω
I_D	10A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, ultra low on-resistance and cost-effectiveness.

The SO-8 package is widely preferred for commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current ³	10	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current ³	8	A
I_{DM}	Pulsed Drain Current ¹	30	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation	2	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	62.5	$^\circ\text{C}/\text{W}$



AP4224LGM-HF

Electrical Characteristics @ $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=4.5V, I_D=10A$	-	-	14	m Ω
		$V_{GS}=2.5V, I_D=7A$	-	-	23	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.3	-	1.2	V
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=10A$	-	16	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=16V, V_{GS}=0V$	-	-	10	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
Q_g	Total Gate Charge	$I_D=11A$	-	10	-	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=15V$	-	3	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=4.5V$	-	4.5	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15V$	-	9	-	ns
t_r	Rise Time	$I_D=1A$	-	5	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega$	-	21	-	ns
t_f	Fall Time	$V_{GS}=10V$	-	4.5	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	1100	-	pF
C_{oss}	Output Capacitance	$V_{DS}=15V$	-	140	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	100	-	pF
R_g	Gate Resistance	$f=1.0\text{MHz}$	-	1.3	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_S=1.7A, V_{GS}=0V$	-	-	1.2	V
t_{rr}	Reverse Recovery Time	$I_S=11A, V_{GS}=0V,$	-	17	-	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=100A/\mu s$	-	8	-	nC

Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse test
3. Surface mounted on 1 in² copper pad of FR4 board ; 135 °C/W when mounted on min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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